# 501954567 06/13/2012

## PATENT ASSIGNMENT

Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

## **CONVEYING PARTY DATA**

Name	Execution Date
Wei Qiang Jin	06/05/2012
Ding Hui Xu	06/05/2012

#### RECEIVING PARTY DATA

Name:	STATS ChipPAC Ltd.
Street Address:	10 Ang Mo Kio Street 65
Internal Address:	#05-17/20 Techpoint
City:	Singapore
State/Country:	SINGAPORE
Postal Code:	569059

## PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13489850

#### CORRESPONDENCE DATA

Fax Number: (408)738-0881 Phone: 408-738-0592

Email: efiling@ishimarulaw.com

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US

Mail.

Correspondent Name: ISHIMARU & ASSOCIATES LLP

Address Line 1: 2055 Gateway Place

Address Line 2: Suite 700

Address Line 4: San Jose, CALIFORNIA 95110

ATTORNEY DOCKET NUMBER: 27-850

NAME OF SUBMITTER: Stanley Chang

Total Attachments: 2

source=27-850\_Assignment#page1.tif source=27-850\_Assignment#page2.tif

PATENT REEL: 028370 FRAME: 0454 00 134898

501954567

Docket No.: 27-850

### ASSIGNMENT

WHEREAS, the undersigned (hereinafter termed Assignor(s)) has/have invented certain new and useful improvements in

# INTEGRATED CIRCUIT PACKAGING SYSTEM WITH INTERPOSER AND METHOD OF MANUFACTURE THEREOF

for which a United States patent application has been executed on or before the date of this assignment;

WHEREAS, <u>STATS ChipPAC Ltd.</u>, a Corporation of the <u>Republic of Singapore</u>, having a place of business at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, Republic of Singapore (hereinafter termed Assignee), is desirous of acquiring the entire right, title and interest in and to said application and said invention and improvements thereon, and in and to Letters Patents thereon when granted in the United States and foreign countries;

NOW, THEREFORE, for good and valuable consideration received by said Assignor(s) from said Assignee(s), the receipt of which is hereby acknowledged by said Assignor(s):

- 1. Said Assignor(s) does hereby sell, assign, transfer and convey unto said Assignee(s), the entire right, title and interest in and to said application and said invention and in and to any and all improvements on said invention and in and to any and all improvements on said invention heretofore or hereafter made or acquired by said Assignor(s); and in and to any and all Letters Patent on said invention and/or said improvements that may be granted in the United States or any foreign country, including each and every Letters Patent granted on any application which is a division, continuation, substitution, renewal, or continuation-in-part of any said application, and in and to each and every reissue or extension of said Letters Patent.
- 2. Said Assignor(s) hereby covenants and agrees to cooperate with said Assignee(s) where said Assignee(s) may enjoy to the fullest extent the right, title and interest herein conveyed. Such cooperation shall include (a) prompt execution of all papers (prepared at the expense of Assignee(s)) which are deemed necessary or desirable by Assignee(s) to perfect in it the right, title and interest herein conveyed, (b) prompt execution of all petitions, oaths, specifications or other papers (prepared at the expense of Assignee(s)) which are deemed necessary or desirable by Assignee(s) for prosecuting said application, for filing and prosecuting divisional, continuation, substitution, renewal, continuation-in-part, or additional applications in the United States and/or foreign countries covering said invention and/or said improvements, for filing and prosecuting applications for reissuance of letters patent included herein, or for interference proceedings involving said invention and/or said improvements and (c) prompt assistance and cooperation in the prosecution of interference proceedings involving said invention and/or said improvements and in the adjudication of said Letters Patent, particularly by the disclosure of facts and the production of evidence relating to said invention and/or said improvements, provided the expenses which may be incurred by said Assignor(s) in lending such assistance and cooperation shall be paid by the Assignee(s).
- 3. The terms, covenants and conditions of this assignment shall inure to the benefit of said Assignee(s), its successors, assigns and/or other legal representatives and shall be binding upon said Assignor(s), his/her heirs, legal representatives and assigns.

1 of 2

Docket No.: 27-850

ASSIGNMENT

- 4. Said Assignor(s) hereby warrants and represents that he/she has not entered into any assignment, contract or understanding in conflict herewith.
- 5. Said Assignor(s) hereby authorizes and requests the attorney(s) of record in this application to insert the serial number and filing date of this Non Provisional application in the spaces that follow:

Serial Number:	13/489,850	Filing Date:	June 6, 2012
	DF, the said Assigno	or has executed and	delivered this instrument on
the date set forth below.			
不多强		2012/615	
Wei Qian	g Jin	Date	
	) A	扬	y Fg
Witness Si	gnature	Witn	ess Signature
Xin	Jín		oli Yu
Print Witne	ess Name	Print	Witness Name
Jun	05. 2012		w12.65
Date		Date	

IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.

No rail	Jun 05. 2012
Ding Hui Xu	Date
\$ \\ \hat{k}	166 41 M
Witness Signature	Witness Signature
Xin Jin	Xiaoli Yu
Print Witness Name	Print Witness Name
Jun 05. 2012	2.6.5
Date	Date